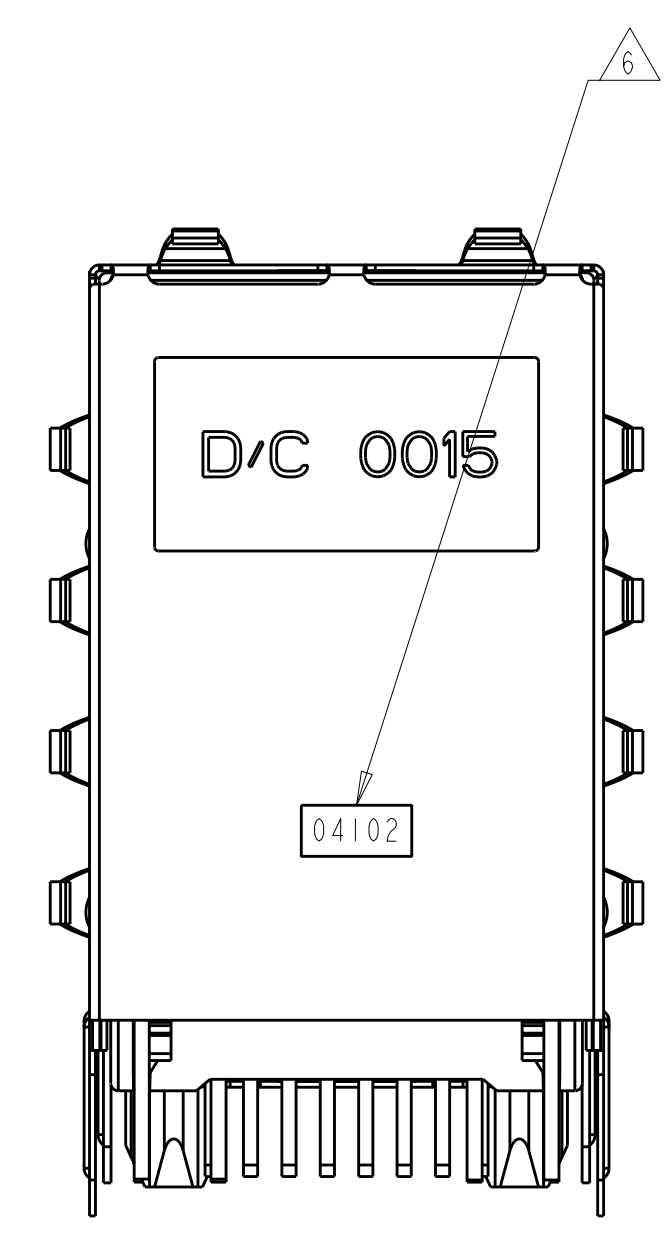
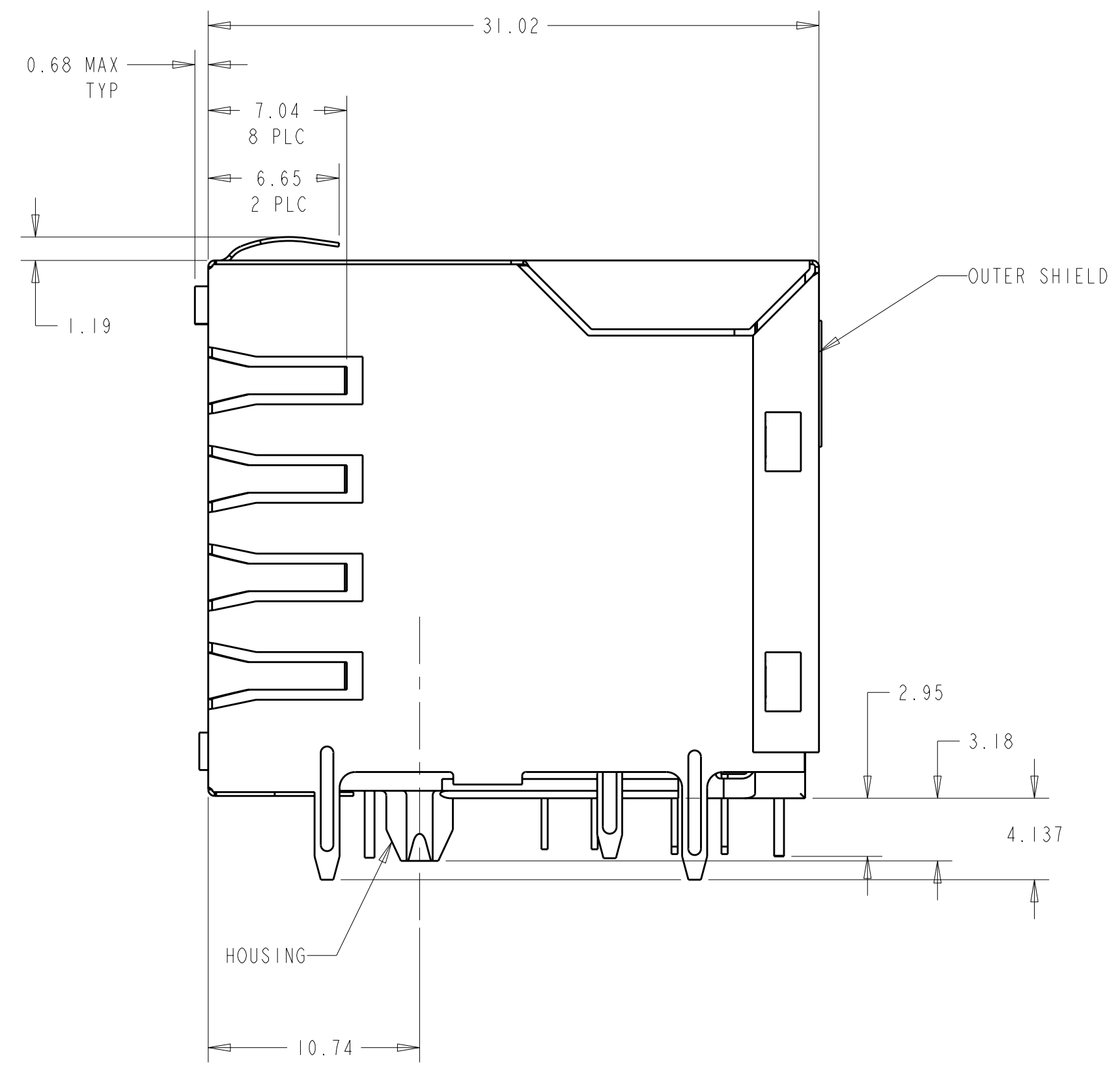
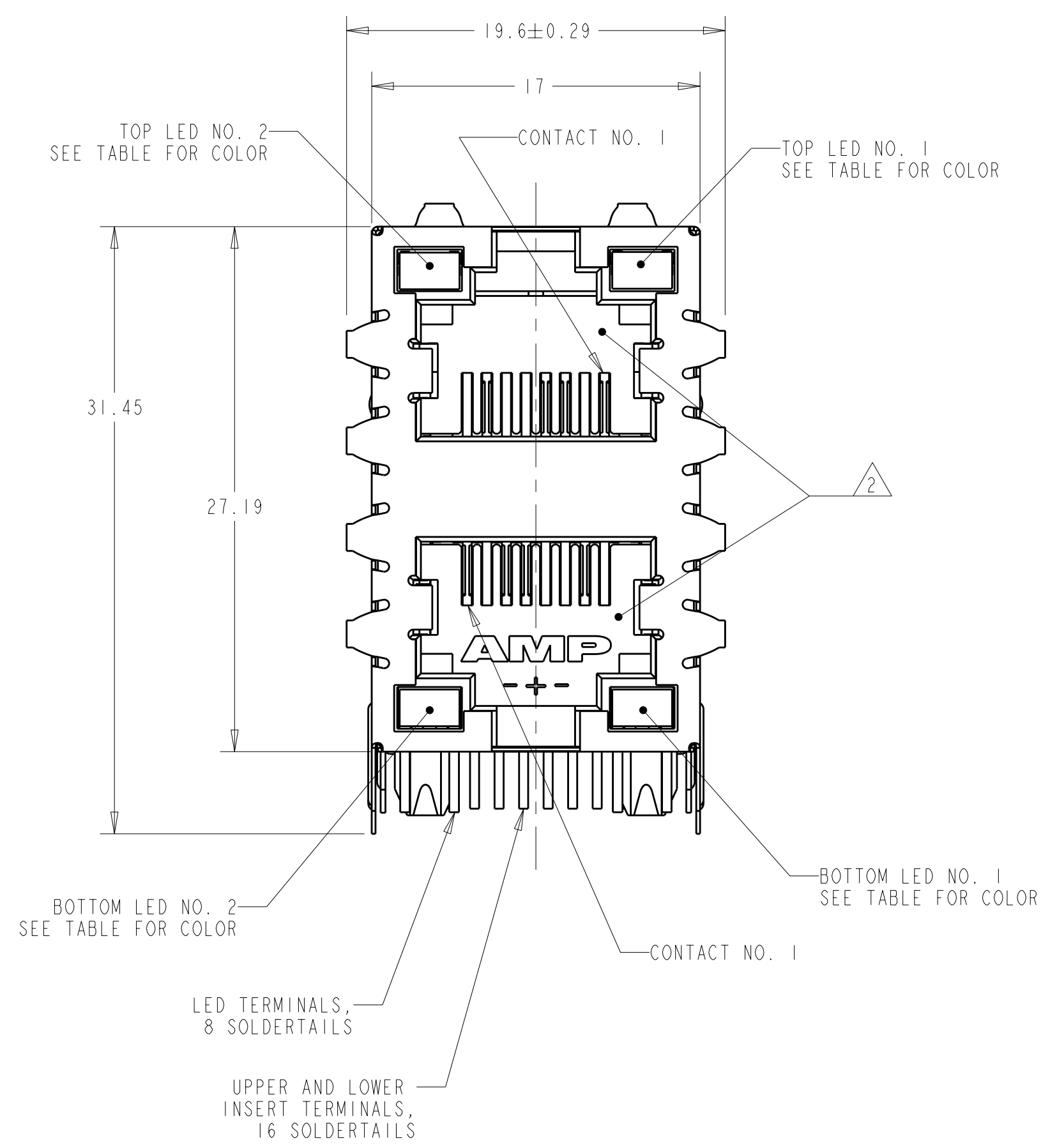
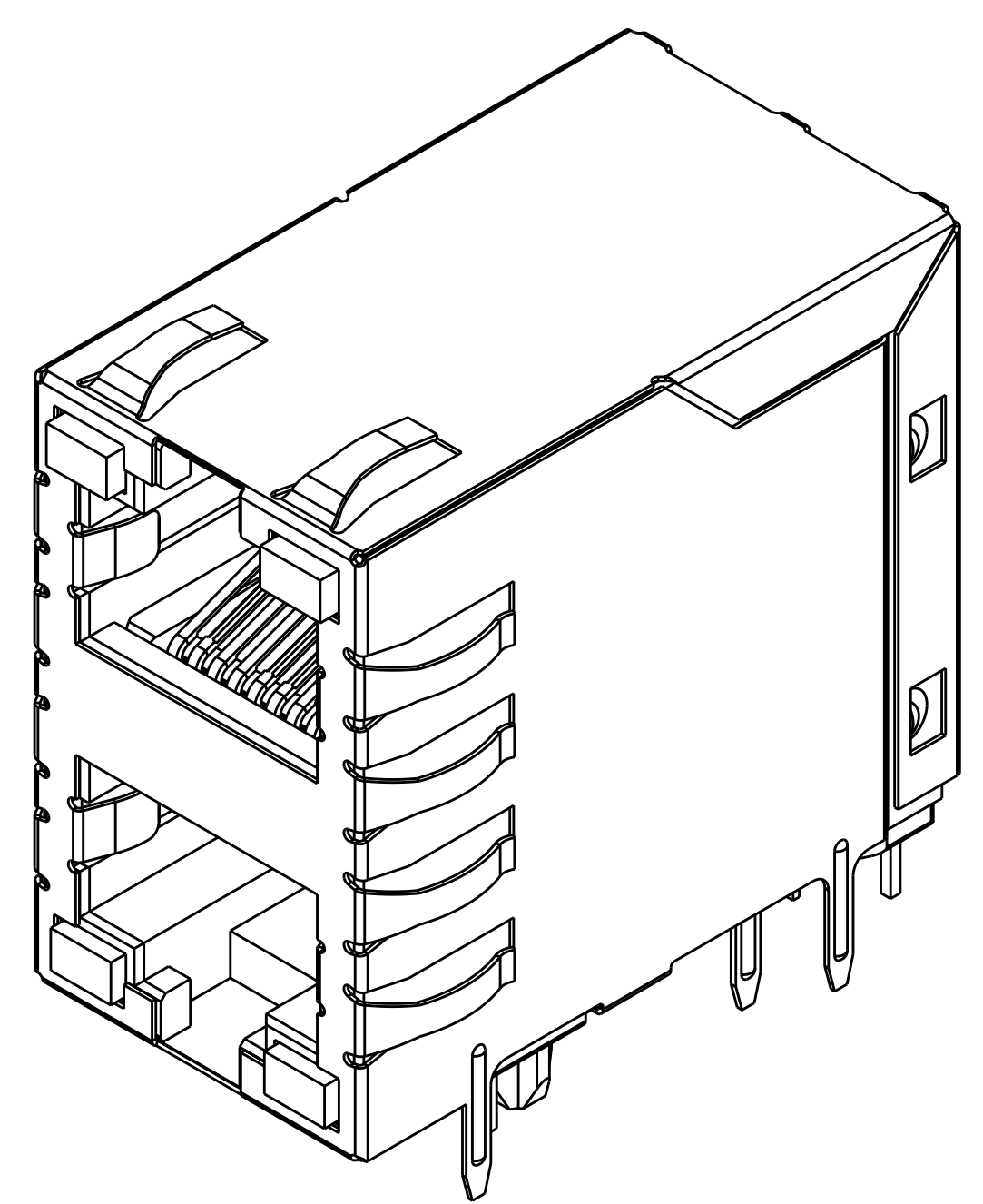
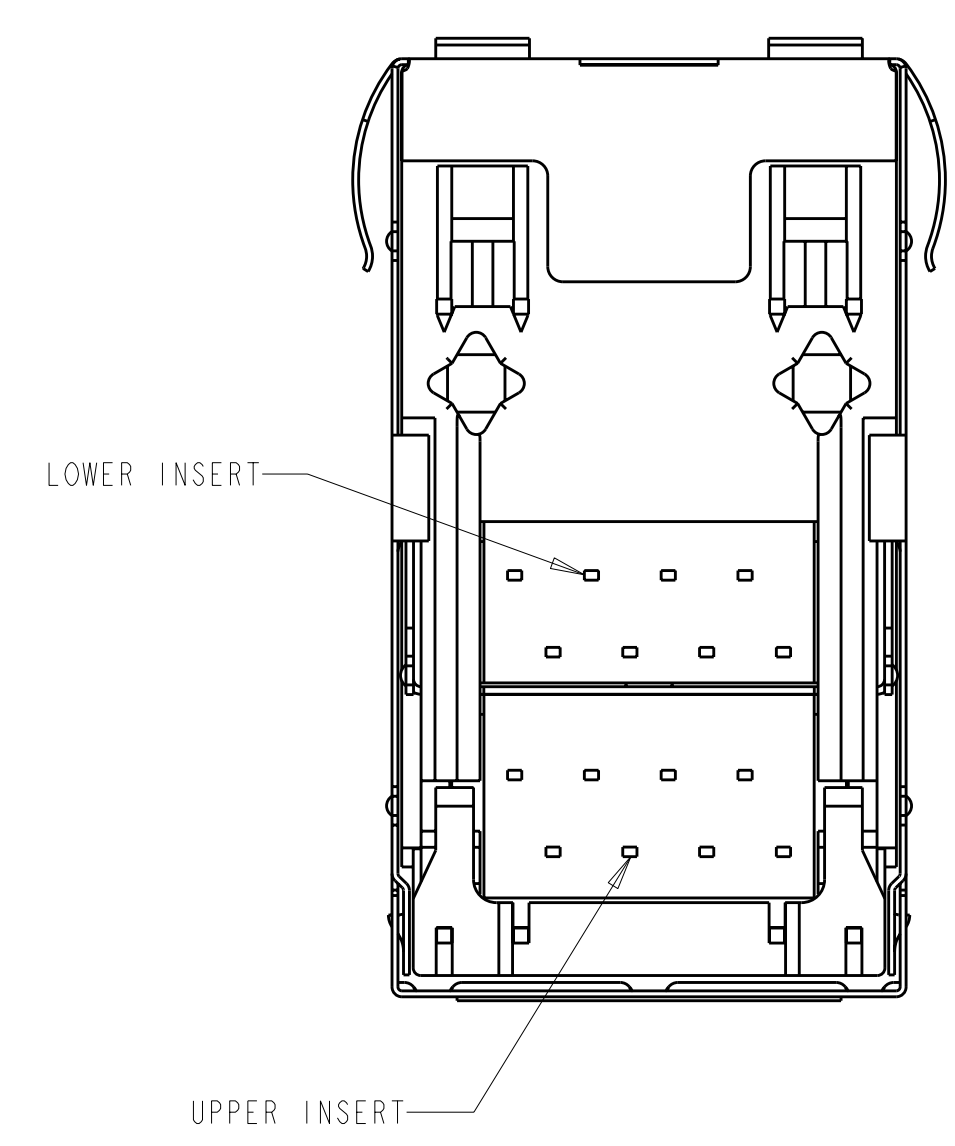


LOC	DIST	REVISIONS			
ES	00	REV	DATE	BY	APPD
		A	31AUG2009	TY	SY
		B	9MAR2010	DZ	SY

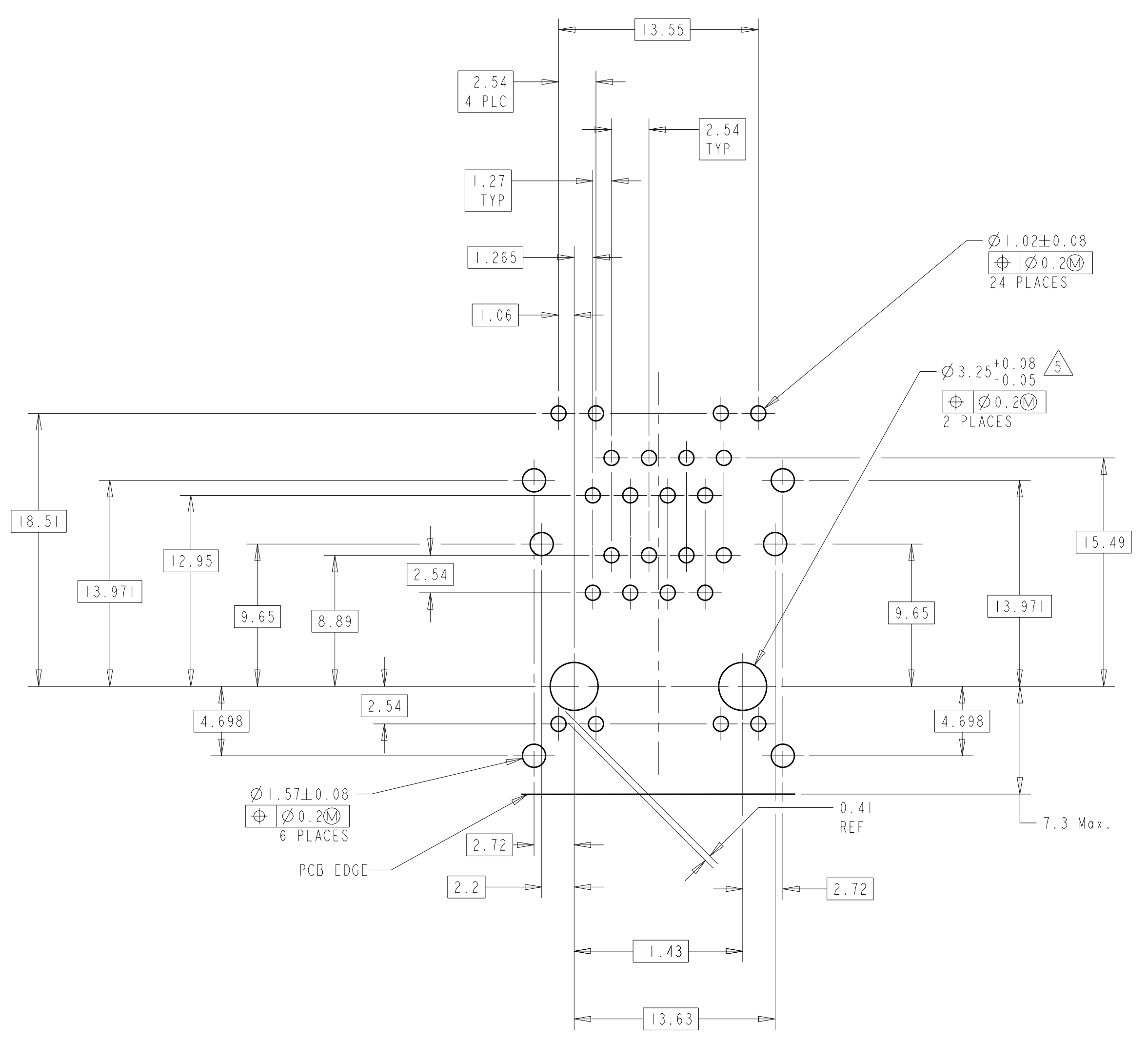


- 1. MATERIAL: HOUSING - PBT POLYESTER, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY-HTN
- TERMINALS - 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27um MINIMUM THICK HARD GOLD IN LOCALIZED MATING INTERFACE AND 3.81um MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27um MINIMUM THICK NICKEL UNDERPLATE.
- OUTER SHIELD - 0.196 THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- INNER SHIELD - 0.25 THICK COPPER ALLOY PLATED WITH 2.03 um MINIMUM BRIGHT TIN OVER 1.27 um MINIMUM NICKEL UNDERPLATE.
- LIGHT EMITTING DIODE (LED) - DIFUSED EPOXY LENS, 0.51 X 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 um THICK Sn/Cu OVER 2.03 um THICK Ag OVER 1.02 um THICK Cu OVER 3.56 um THICK Ni OVER 1.02 um Cu UNDERPLATE
- 2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3. SUGGESTED OPERATING CURRENT FOR THE LED IS 20mA.
- 4. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.
- 5. USE NO. 30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- 6. DATE CODE LOCATED ON REAR OF PART APPROX AS SHOWN: FIRST 2 DIGITS ARE LAST 2 DIGITS OF YEAR, SECOND 2 DIGITS ARE MANUFACTURING WORK WEEK, LAST DIGIT IS DAY OF WEEK, WITH SUNDAY=1.
- 7. MATERIAL: HOUSING - PBT POLYESTER, BLACK, UL 94V-0. OVERMOLDED TERMINAL ARRAY-HTN
- TERMINALS - 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27um MINIMUM THICK HARD GOLD IN LOCALIZED MATING INTERFACE AND 3.81um MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27um MINIMUM THICK NICKEL UNDERPLATE.
- OUTER SHIELD - 0.196 THICK COPPER ALLOY PLATED WITH 1.27 um [.000050] MINIMUM NICKEL AND 2.03 um [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
- INNER SHIELD - 0.25 THICK COPPER ALLOY PLATED WITH 2.03 um MINIMUM MATTE TIN OVER 1.27 um MINIMUM NICKEL UNDERPLATE.
- LIGHT EMITTING DIODE (LED) - DIFUSED EPOXY LENS, 0.51 X 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 um THICK Sn/Cu OVER 2.03 um THICK Ag OVER 1.02 THICK Cu OVER 3.56 um THICK Ni OVER 1.02 um Cu UNDERPLATE
- 8. OPERATING TEMPERATURE FROM -40 °C TO +80 °C

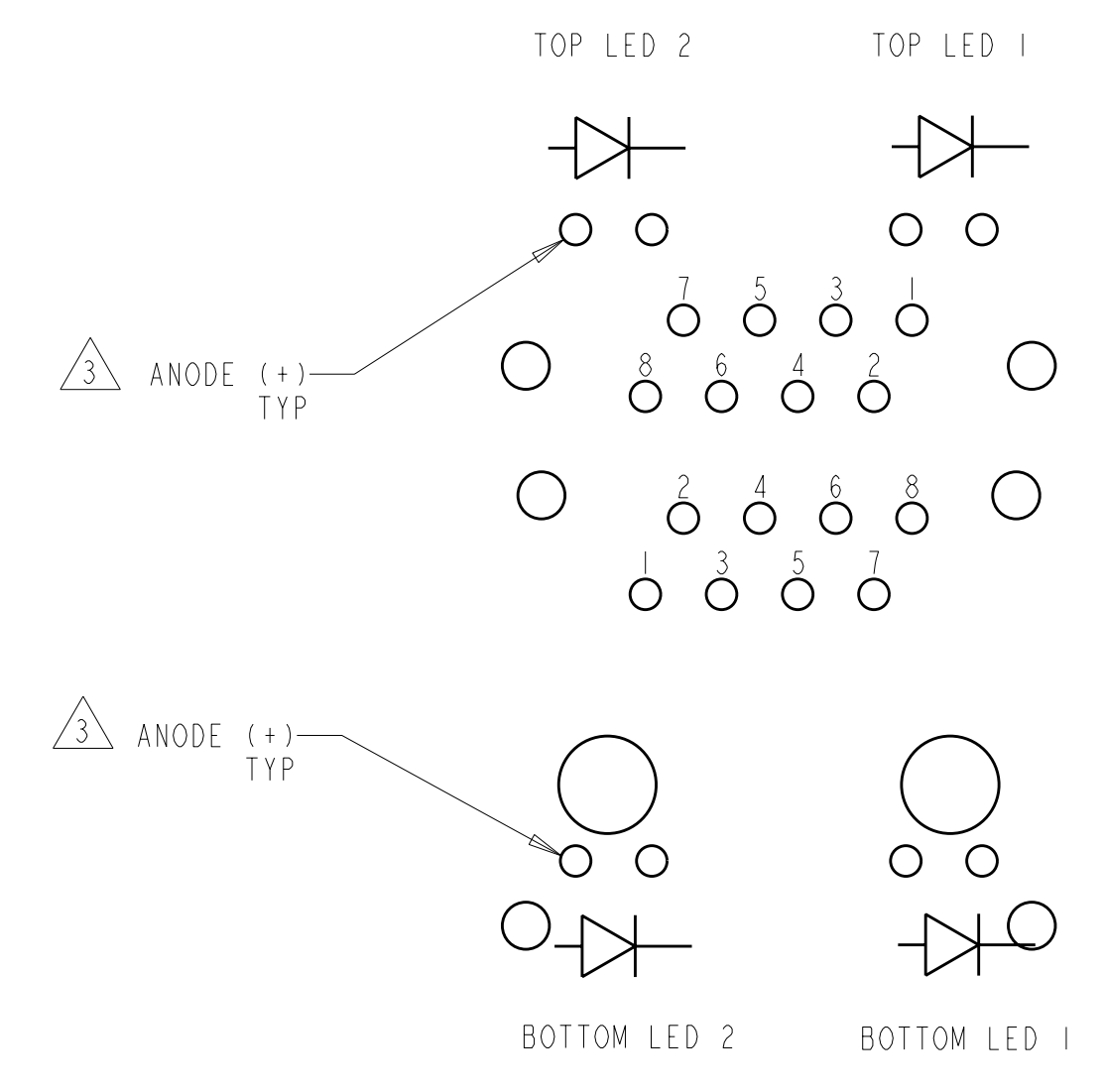


DIMENSIONS:		TOLERANCES UNLESS OTHERWISE SPECIFIED:		DWN		Tyco Electronics	
mm	0 PLC ±	1 PLC ±	2 PLC ±0.25	3 PLC ±0.25	4 PLC ±	22JUN2009	Tyco Electronics Corporation Shanghai, P.R. China, 200233
	ANGLES ±	FINISH	SEE NOTE 1,7	NAME	MODULAR JACK ASSEMBLY, STACKED, 2 X 1, 8 POSITION, SHIELDED, PANEL GROUND, LED, CATEGORY 5	DATE	1932391-2
MATERIAL	SEE NOTE 1,7	WEIGHT	-	PRODUCT SPEC	108-1163-2	BY	1932391-1
		CUSTOMER DRAWING		APPLICATION SPEC	114-2154	APPD	
		SCALE	1:1	SIZE	00779	REV	2

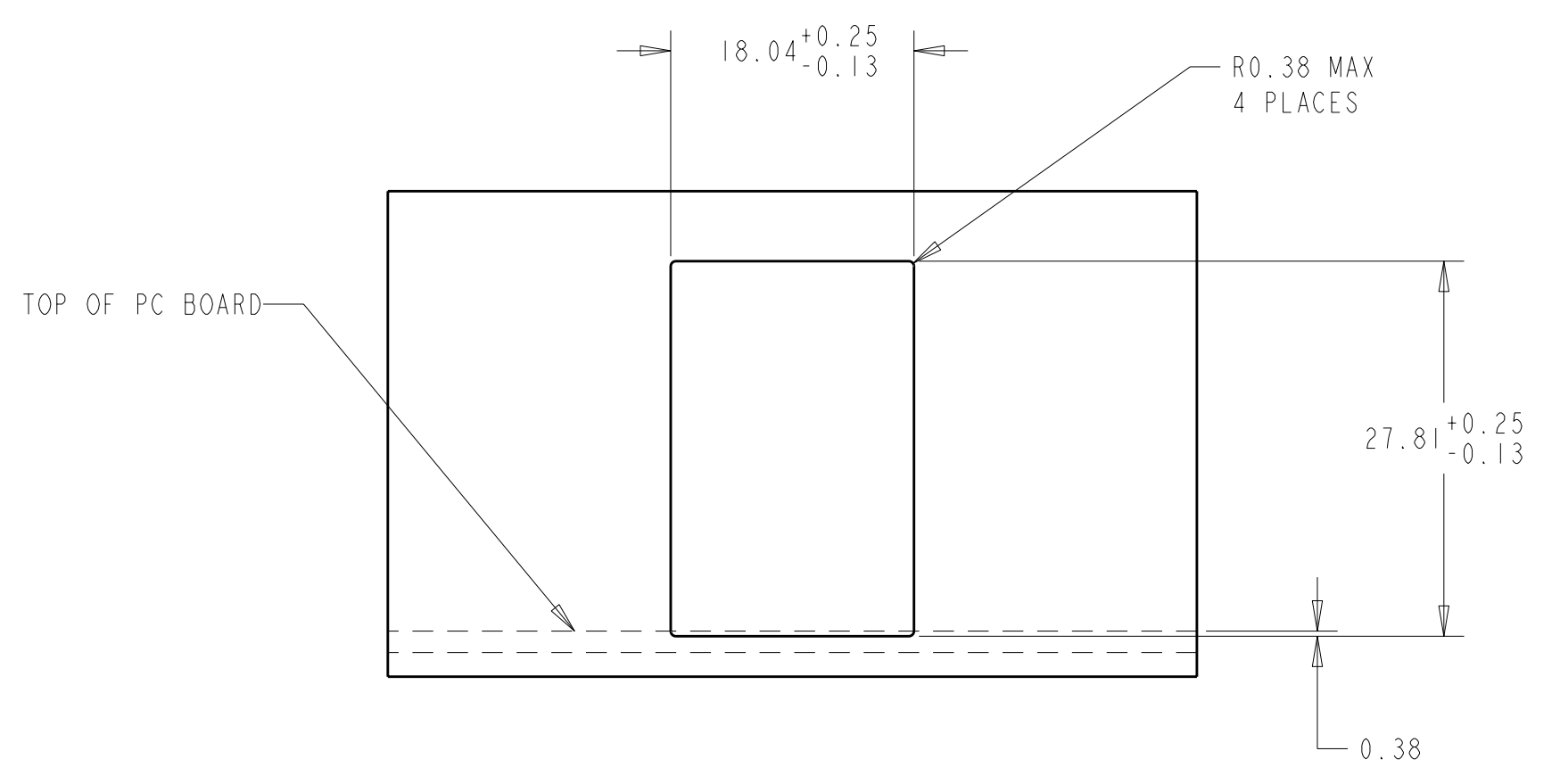
LOC	DIST	REVISIONS			
ES	00	REV	DATE	BY	APPD
		1	SEE SHEET 1		



PC BOARD LAYOUT VIEWED FROM COMPONENT SIDE OF BOARD  
 SCALE 4:1



SCALE 4:1



SUGGESTED PANEL CUTOUT DIMENSIONS  
 SCALE 2:1

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED. THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED. THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED.</small>		DWN: D. ZHU 22JUN2009 CHK: M. LI 22JUN2009 APVD: S. YAO 22JUN2009	Tyco Electronics Corporation Shanghai, P.R. China, 200233
DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 1 PLC ±0.25 5 PLC ±0.25 4 PLC ± ANGLES ±	NAME: MODULAR JACK ASSEMBLY, STACKED, 2 X 1, 8 POSITION, SHIELDED, PANEL GROUND, LED, CATEGORY 5 PRODUCT SPEC: 108-1163-2 APPLICATION SPEC: 114-2154	SIZE: A1 CAGE CODE: 00779 DRAWING NO: C=1932391
MATERIAL: SEE NOTE 1	FINISH: SEE NOTE 1	WEIGHT: -	RESTRICTED TO: -
CUSTOMER DRAWING		SCALE: 1:1	SHEET 2 OF 2 REV A1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)